

TANK-870e-H110

- High-Performance 6th/7th Generation Intel® Core™ Processor
- Fanless Embedded Computer



Features

- 6th/7th Gen Intel® Core™ processor platform with Intel® H110 chipset and DDR4 memory
- Support dual display VGA+HDMI
- On-board internal power connector for providing power to add-on cards
- Great flexibility for hardware expansion



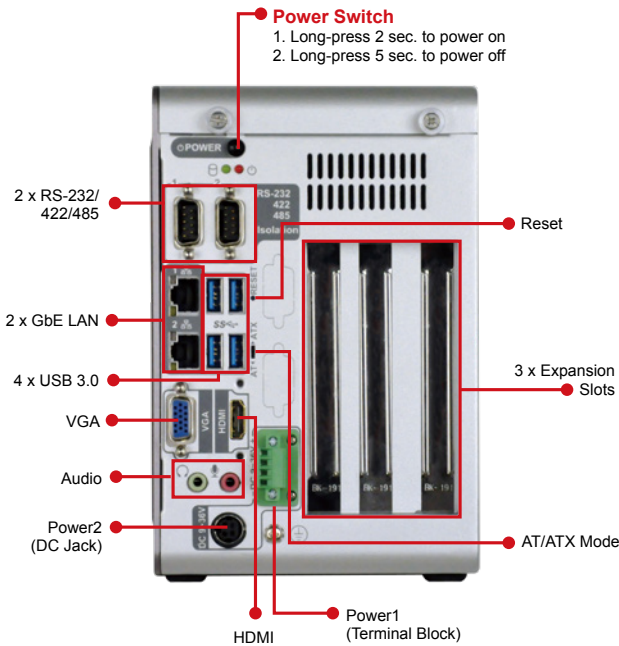
Specifications

| Model Name | | TANK-870e-H110 |
|----------------|--------------------------|--|
| Chassis | Color | Dark silver purple + Silver |
| | Dimensions (WxDxH) (mm) | 132.6 x 255.2 x 190 |
| | System Fan | Fanless |
| | Chassis Construction | Extruded aluminum alloys |
| Motherboard | CPU | Intel 7th Gen Core CPU & Intel® Core™ i7-6700TE (2.4 GHz, quad-core, TDP=35W) Intel® Core™ i5-6500TE (2.3 GHz, quad-core, TDP=35W) |
| | Chipset | Intel® H110 |
| | System Memory | 2 x 260-pin DDR4 SO-DIMM, one 4 GB pre-installed (system max: 32GB) |
| Storage | Hard Drive | 1 x 2.5" SATA 6Gb/s HDD/SSD bay |
| I/O Interfaces | USB 3.0 | 4 |
| | Ethernet | 2 x RJ-45 PCIe GbE by RTL8111G controller |
| | COM Port | 2 x RS-232/422/485 (DB-9, w/ 2.5kV isolation protection) |
| | Display | 1 x VGA, 1 x HDMI 1.4 |
| | Resolution | VGA: Up to 1920 X 1200@60Hz HDMI 1.4: Up to 4096x2160@24Hz |
| | Audio | 1 x Line-out ; 1 x Mic-in |
| | Wireless | 1 x 802.11a/b/g/n/ac (optional) |
| Expansions | Backplane | 3A: 1 x PCIe x16 , 2 x PCI 3B: 1 x PCIe x16 , 1 x PCIe x4, 1 x PCI 3C: 3 x PCI |
| | PCIe Mini | 1 x Full-size PCIe Mini slot 1 x Full-size PCIe Mini slot (supports mSATA, colay with SATA) |
| Power | Power Input | DC Jack: 9 V~36 V DC Terminal Block: 9 V~36 V DC |
| | Power Consumption | 19 V@3.44 A (Intel® Core™ i7-6700TE with 8 GB memory) |
| | Internal Power Connector | 5V@3A or 12V@3A |
| Reliability | Mounting | Wall mount & DIN Rail |
| | Operating Temperature | i7-6700TE -20°C ~ 50°C with air flow (SSD), 10% ~ 95%, non-condensing i5-6500TE -20°C ~ 60°C with air flow (SSD), 10% ~ 95%, non-condensing |
| | Storage Temperature | -40°C ~ 85°C with air flow (SSD), 5% ~ 90%, non-condensing |
| | Operating Shock | Half-sine wave shock 5G, 11ms, 100 shocks per axis |
| | Non-Operating Shock | Half-sine wave shock 15G, 11ms, 100 shocks per axis |
| | Operating Vibration | MIL-STD-810G 514.6C-1 (with SSD) |
| | Non-Operation Vibration | Half-sind mode IEC-60068-2-06 |
| | Weight (Net/Gross) | 4.2 kg/6.3 kg |
| Safety/EMC | CE/FCC | |
| OS | Supported OS | Microsoft® Windows® 8 Embedded, Microsoft® Windows® Embedded Standard 7 E, Microsoft® Windows® 10 IoT Enterprise |

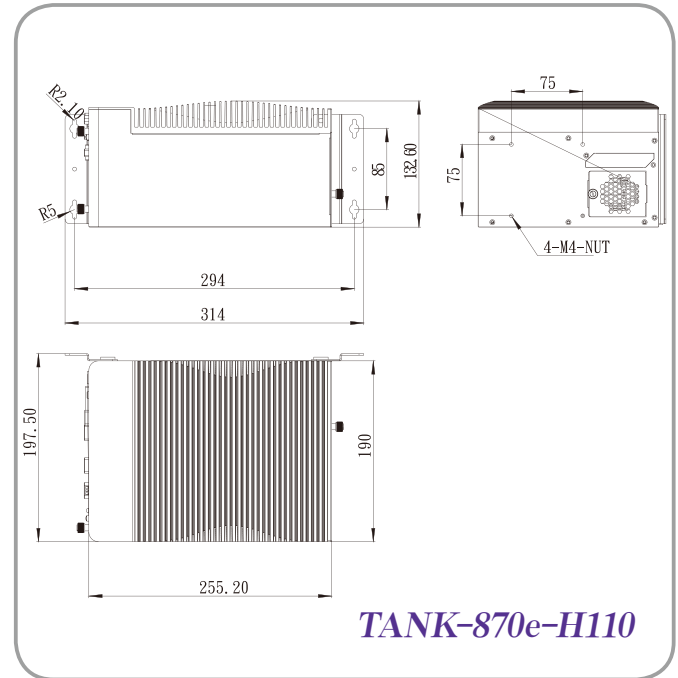
Versatile Expansion Interface

| Backplane | 3A HPE-3S6 | | 3B HPE-3S7 | | | 3C HPE-3PCI |
|-----------|------------|--------------|------------|-------------|--------------|-------------|
| Slot | 2 x PCI | 1 x PCIe x16 | 1 x PCI | 1 x PCIe x4 | 1 x PCIe x16 | 3 x PCI |
| Signal | PCI | PCIe x16 | PCI | PCIe x1 | PCIe x16 | PCI |

Fully Integrated I/O



Dimensions (Unit: mm)



TANK-870e-H110

Ordering Information

| Part No. | Description |
|-----------------------------|--|
| TANK-870e-H110-i5/4G/3A-R10 | Ruggedized Fanless embedded system with Intel® Core i5-6500TE 2.3GHz, (up to 3.3 GHz, Quad Core, TDP 35W), 4GB DDR4 pre-installed memory, 1 x PCIe by 16 & 2 x PCI expansion, VGA/HDMI, 9~36V DC, RoHS |
| TANK-870e-H110-i5/4G/3B-R10 | Ruggedized Fanless embedded system with Intel® Core i5-6500TE 2.3GHz, (up to 3.3 GHz, Quad Core, TDP 35W), 4GB DDR4 pre-installed memory, 1 x PCIe by 16 & 1 x PCIe by 1 & 1 x PCI expansion, VGA/HDMI, 9~36V DC, RoHS |
| TANK-870e-H110-i5/4G/3C-R10 | Ruggedized Fanless embedded system with Intel® Core™ i5-6500TE 2.3 GHz (up to 3.3 GHz, quad core, TDP 35W), 4GB DDR4 pre-installed memory, 3 x PCI expansion, VGA/HDMI, 9~36V DC, RoHS |
| TANK-870e-H110-i7/4G/3A-R10 | Ruggedized Fanless embedded system with Intel® Core i7-6700TE 2.4GHz, (up to 3.4 GHz, Quad Core, TDP 35W), 4GB DDR4 pre-installed memory, 1 x PCIe by 16 & 2 x PCI expansion, VGA/HDMI, 9~36V DC, RoHS |
| TANK-870e-H110-i7/4G/3B-R10 | Ruggedized Fanless embedded system with Intel® Core i7-6700TE 2.4GHz, (up to 3.4 GHz, Quad Core, TDP 35W), 4GB DDR4 pre-installed memory, 1 x PCIe by 16 & 1 x PCIe by 1 & 1 x PCI expansion, VGA/HDMI, 9~36V DC, RoHS |
| TANK-870e-H110-i7/4G/3C-R10 | Ruggedized Fanless embedded system with Intel® Core™ i7-6700TE 2.4 GHz (up to 3.4 GHz, quad core, TDP 35W), 4GB DDR4 pre-installed memory, 3 x PCI expansion, VGA/HDMI, 9~36V DC, RoHS |

Options

| Part No. | Description |
|-----------------------------|---|
| 32702-000400-200-RS | European power cord |
| 63040-010120-210-RS | Power adapter, FSP120-ABBN2, 9NA1205302, Active PFC, Vin:90~264VAC, 120W, plug=6.5mm, cable=1500mm, Erp (no load 0.15W), Vout:19VDC, 4-pin DIN with lock, CCL, RoHS |
| 19Z00-000630-00-RS | Fan, +12V DC, 4-pin, 40 mm x 40 mm x10 mm, 6500RPM, RoHS |
| EMB-WIFI-KIT11-R20 | 1T1R wifi module kit for embedded system, IEEE802.11a/b/g/n/ac WiFi with Bluetooth 4.0/3.0+HS, 1 x wifi module, 2 x 400mm RF cable, 2 x Antenna, RoHS |
| DK-75-R10 | DIN mount kit adapter for VESA-75 |
| TANK-870e-H110-WES7E64-R10 | OS Image with Windows® Embedded Standard 7 E 64-bit for TANK-870e-H110 Series, with DVD-ROM, RoHS |
| TANK-870e-H110-W10E64-H-R10 | OS Image with Windows Embedded Standard 10 E High End 64-bit for TANK-870e-H110-i7 Series, with DVD-ROM, RoHS |
| TANK-870e-H110-W10E64-V-R10 | OS Image with Windows Embedded Standard 10 E Value 64-bit for TANK-870e-H110-i5 Series, with DVD-ROM, RoHS |

Packing List

| | |
|-------------------|----------------------|
| 1 x Chassis Screw | 1 x Mounting Bracket |
|-------------------|----------------------|